



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Kie Y. Ahn et al.

Title: METHODS FOR MAKING COPPER AND OTHER METAL INTERCONNECTIONS IN  
INTEGRATED CIRCUITS

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Attn: MAIL STOP ISSUE FEE

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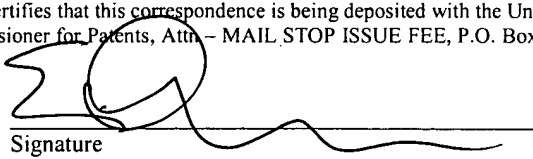
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